**Minutes – 030918**

**Present: HH, SW, AG, DS, SB, TJ**

**Apologies: PS, JT**

**Strip modules**

Liam starts 3rd Sep.

Glued 2 hybrids for 2nd module. 1 by liam. Liam was better ☺

This week, liam will wire bond. Power board to be received this week. Aim to ship 2 modules to RAL this week.

Mini sensors glued to heat sink for measurement. Share work load with Paul and Jon. Results needed for ITk week. We have 6 samples for Santa Cruz. A month work of Alibaba measurements. Measurement at 1V, do analysis, do next voltage and repeat.

Module frame version ? finished on Friday. Documenting today. Stevenage sent layouts to cross check stack-ups. Visit in next 2 weeks. Expected 21 day turnaround. Both technical and possible procurement. Evidence from test coupons suggest our stack up is ok.

TJ to write up hybrid vibration study. Shaken off 8 wirebonds. (to investigate pixel bump bonds?).

EOS pdr. DCS power block is Ashley’s design.

Asked to do documents for procedure documents for QA/QC.

**Strip Mechanics**

Making good progress, with changes . ready for honey comb this week. Need grinder this week. Still have till end of this month before Hamish leaves. C-channels today. One has holes for locating.

Replace one piece of peek with CF. honeycomb isn’t big enough: will be done jigsaw/Tetris style.

TJ has not seen metal for jig. (Jon smuggled it in )

Hamish is documenting. There is time lapse video of process. New scales are working well (upto 650g). Slightly complicated to use. 10 minutes to tare.

**Pixel modules**

1st modules for module mounting are at RAL. One with wirebonding, one with out. Liverpool and Glasgow need to start building. We have silicon. Ilya away until Wednesday.

HH to ask Ilya if we still need frame. Ilya has designed board. Need to find Akhil to make board.

On Wednesday, start measuring silicon. Measuring IVs.

Liverpool to prepare 3 slides. For module meeting. To be part of sensor market survey. (Jon, Paul… support by Ilya). Jon/Paul to prepare slides. Jon/Paul to present.

Yarr is working ! just need to test chip. Wait until wednesday. New student arriving on Tuesday. He has desk on 2nd floor.

Charge collection measurements for strip chips. 15 sensors. Strontium 90. Needed for MS.

Irradiations are going ahead at Birmingham. 2 done at kitt. 2 to go to Birmingham. 4 more for paralene coating. Meeting on HV protection this week.

**Pixel Mechanics**

**Stalled whilst PS away.**

TJ and SB to write spec doc.

TJ has emailed Danilo G. TJ to email outer barrel and inner pixel people, and cc Danilo.

Wednesday: milestones for pixel structures.

*Have quotes for CF – much more expensive that we originally though. We are now asking for cyanate ester*

*Do we really need the expensive one? We have experience through the face sheets.*

* *As PC to follow up.*

**AOB**

**HH-> get pizza night date.**

SW to sort travel documentation.

TJ on stave core assembly. – project overview talk.

LAU: HH to book vc room.

AG to investigate topics for ITk week.